SCOPE :

This specification applies to the Pb Free high current type SMD inductors for MSCDRI-125AH0-SERIES

Warn : This product series can't be used in synchronous rectification circuit that is over 24V.

PRODUCT INDENTIFICATION



- ① Product Code
- ② Dimensions Code
- ③ AEC-Q200 Code
- ④ Inductance Code
- **⑤** Tolerance Code

(1) SHAPES AND DIMENSIONS



(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L : HP 4284A PRECISION LCR METER (or equivalent)

RDC : CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

(3) CHARACTERISTICS

(3)-1 Operate temperature range $-40^{\circ}C \sim +155^{\circ}C$ (Including self temp. rise)



TABLE 1

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated D	C Current	Morking
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω)Max.	Isat (A)	Irms (A)	warking
MSCDRI-125AH0-100	10	M,N	100kHz/0.25V	26.5m	7.20	5.60	100
MSCDRI-125AH0-150	15	M,N	100kHz/0.25V	31.9m	5.80	5.00	150
MSCDRI-125AH0-220	22	M,N	100kHz/0.25V	46.3m	4.50	4.00	220
MSCDRI-125AH0-330	33	M,N	100kHz/0.25V	66.3m	4.00	3.50	330
MSCDRI-125AH0-470	47	M,N	100kHz/0.25V	92.5m	3.24	2.90	470
MSCDRI-125AH0-101	100	М	100kHz/0.25V	0.17	2.00	2.20	101
MSCDRI-125AH0-221	220	М	100kHz/0.25V	0.43	1.60	1.39	221
MSCDRI-125AH0-271	270	М	100kHz/0.25V	0.45	1.50	1.32	271

% □ specify the inductance tolerance,M(±20%),N(±30%)

%Isat : Based on inductance change (\triangle L/Lo : drop 25% Max.) @ambient temperature 25 $^{\circ}$ C

Irms :Based on temperature rise ($\triangle T$: 40°C TYP.)

Rated DC Current: The less value which is lsat or Irms.



(4) RELIABILITY TEST METHOD

ELECTRICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Temperature	∆L/L20℃≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85 $^{\circ}\!\mathrm{C}$,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be $ riangle L/L20^\circ\!C \leq \pm 10\%$.

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board
	There shall be	in figure 1 and a load applied unitil the figure in the arrow
	no mechanical	direction is made approximately 3mm.
	damage or elec-	60 sec minimum holding time.
	trical damage.	PCB dimension shall the page 7/9
		F(Pressurization)
		$\overline{\nabla}$
		10 20 R340
		PRESSURE ROD figure-1
Flammability	There shall be	Burning stops within 10 seconds on a vertical specimen; drips of
	no other	particles allowed as long as they are not inflamed.
	damage or	
	problems.	
Terminal Strength	There shall be	With the component mounted on a PCB obtained from the Supplier with the device to be tested apply a 17.7 N (1.8 Kg) force
	no other	to the side of a device being tested. This force shall be applied for
	damage or	60 +1 seconds.
	problems.	
Mechanical Shock	∆L/Lo≦±5%	100g's/6ms/Half-sine/12.3ft/sec
	There shall be	
	no mechanical	
	damage.	



MECHANICAL

TEST ITEM	SPECIFICATION			
Vibration	∆L/Lo≦±5%	5g's for 20 minutes, 12 cycles each of 3 orientations.		
		Test from 10-2000 Hz.		
	There shall be			
	no mechanical			
	damage.			
Solderability	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated		
	More than 90%	over the whole of the sample before hard, the sample shall		
		then be preheated for about 2 minutes in a temperature of		
		130 \sim 150 $^\circ\!\!\mathbb{C}$ and after it has been immersed to a depth 0.5mm		
		below for 3±1 seconds fully in molten solder M705 with		
		a temperature of 245±5℃.		
		More than 90% of the electrode sections shall be couered		
		with new solder smoothly when the sample is taken out of		
		the solder bath.		
Resistance to	There shall be	Temperature profile of reflow soldering		
Soldering heat	no damage or	soldering		
(reflow soldering)	problems.	$(\text{Peak temperature } 260 \pm 5^{\circ} \mathbb{C} \text{ 10 sec})$		
		200 30 sec Min		
		ୁମ୍ମ 150 Pre-heating / (230+0 ℃)		
		Slow cooling		
		$\left \begin{array}{c} 0 \\ 0 \\ \end{array} \right = \left \begin{array}{c} 150 \\ 150 \\ \end{array} \right = \left \begin{array}{c} 150 \\ 150 \\ \end{array} \right $ (Stored at room temperature)		
		2 min 10 2 min sec. 2 min. or more		
		└───→ └─→└ ───		
		Solder temperature : 260 ±5°C		
		Dip time: 10 ± 1 seconds		
		The chip shall not crack.		
		wore than 75% of the terminal electrode shall		
		be covered with solder.		
	1			



ENVIROMENT CHARACTERISTICS

TEST ITEM	SPECIFICATION		
High temperature	∆L/Lo≦±5%	1000hrs.at rated operating temperature (e.g. 155°C part	
storage		can be stored for 1000hrs.@ 155°C.Same applies for 125°C	
	There shall be	and 105°C. Unpowered. Measurement at 24±4 hours after test	
	no mechanical	conclusion.	
	damage.		
Temperature	∆L/Lo≦±5%	1000cycles (-40°C to +155°C).Note: If 105°C part or 125°C	
Cycling		part the 1000cycles will be at that temperature.	
	There shall be	Measurement at 24±4hours after test conclusion. 30min	
	no other dama-	maximum dwell time at each temperature extreme.1min.	
	ge of problems	maximum transition time.	
Operational Life	∆L/Lo≦±5%	1000hrs. @155°C. If 105°C or 125°C part will be Tested at that temperature. Measurement at 24+4 hours after test	
	There shall be	conclusion	
	no mechanical		
	damage.		
Biased Humidity	∆L/Lo≦±5%	1000hours 85°C/85%RH. Unpowered.Measurement	
		at 24±4hours after test conclusion.	
	There shall be		
	no mechanical		
	damage.		
Test conditions :			
The sar	nple shall be reflow so	oldered onto the printed circuit board in every test.	



(5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN) Unit:mm



(5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD





(6) PACKAGING (6)-1 CARRIER TAPE DIMENSIONS (mm)



(6)-2 TAPING DIMENSIONS (mm)







(6)-3 REEL DIMENSIONS (mm)





(6)-4 QUANTITY

500 pcs/Reel

The products are packaged so that no damage will be sustained.

Please note that the contents may change without any prior notice due to reasons such as upgrading.

